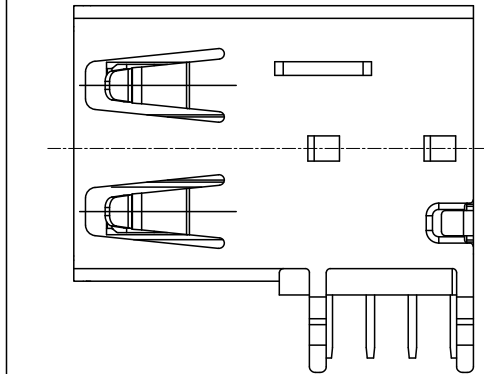
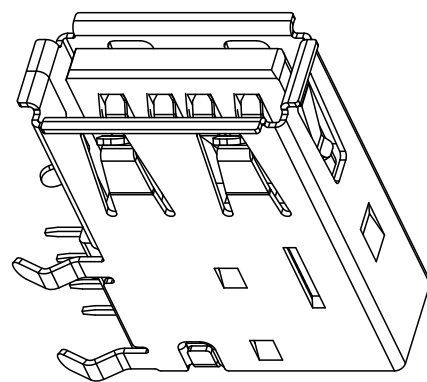


REVISIONS				
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE
A0	N/A		INITIAL RELEASE	/
A1	N/A		图面升级整理图面	2025.05.06

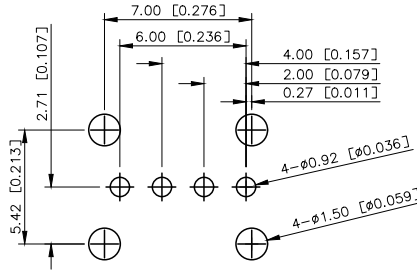


F:Flat

- NOTES:
- 1.MATERIAL SPECIFICATION:
- 1) HOUSING: HIGH TEMP THERMOPLASTIC THERMOPLASTIC UL94V-0. BLACK PBT
 - 2) COVER: HIGH TEMP THERMOPLASTIC THERMOPLASTIC UL94V-0. BLACK PBT
 - 3) SHELL: COPPER ALLOY T=0.30mm
 - 4) BACK COVER: SPCC T=0.30mm
 - 5) CONTACT: C5191 T=0.25mm
- 2.PLATING:
- 1) CONTACT : Pd-Ni30u"+G/F AU CONTACT AREA 80~120u".Bright Tin PLATING ON SOLDER TAILS 50u"Min.Nickel UNDERPLATING OVER ALL
 - 2) SHELL: 50u"Min.Nickel Underplated Over All
 - 3) BACK COVER: 50u"Min.Nickel Underplated Over All
- 3.ELECTRICAL CHARATERISTICS:
- 1) CURRENT RATING: 1A;
 - 2) INSULATION RESISTANCE: 1000MΩ,MIN;
 - 3) CONTACT RESISTANCE: 30mΩ,MAX;
 - 4) DIELECTRIC WITHSTANDING VOLTAGE: 500V AC;
 - 5) OPERATING TEMPERATURE: -25℃~+85℃
- 4.MACHINE CHARACTERISTICS:
- 1) MATING FORCE:3.57 Kgf MAX
 - 2) UNMATING FORCE:1.02 Kgf MIN.

U221-04XN-1BU07-X1

- 1: AU 1U"
5: AU 15U"
6: AU 30U"
- W: WHITE
B: BLACK
- 1: PBT
2: PA6T
3: PA9T
4: LCP
- 1: SPCC
S: Scrolls
F: Flat



RECOMMENDED PCB LAYOUT
COMPONENT SIDE

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERAUCES	



DESIGN	阿树
CHECKED	
APPROVED	

VIEW:	
UNIT:	mm/in
SIZE:	A4

MODEL TYPE:			USB 2.0
PART NO.:			U221-04XN-1BU07-X1
DWG NO.:			
SCALE	PAGE	REVISION	
N/A	1/1	A1	